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February 2015

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FDMC6688P

P-Channel PowerTrench[®] MOSFET -20 V, -56 A, 6.5 m Ω

Features

- Max $r_{DS(on)}$ = 6.5 m Ω at V_{GS} = -4.5 V, I_D = -14 A
- Max $r_{DS(on)}$ = 9.8 m Ω at V_{GS} = -2.5 V, I_D = -11 A
- Max $r_{DS(on)}$ = 20 m Ω at V_{GS} = -1.8 V, I_D = -9 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- Lead-free and RoHS Compliant

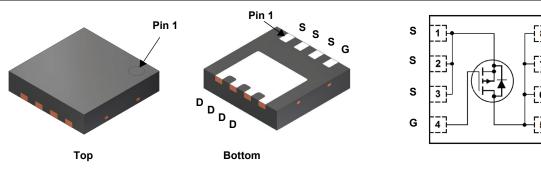


General Description

This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been optimized for $r_{DS(ON)}$, switching performance and ruggedness.

Applications

- Load Switch
- Battery Management
- Power Management
- Reverse Polarity Protection



Power 33

MOSFET Maximum Ratings TA = 25 °C unless otherwise noted

Symbol	Parar		Ratings	Units	
V_{DS}	Drain to Source Voltage			-20	V
V_{GS}	Gate to Source Voltage			±8	V
	Drain Current -Continuous	T _C = 25 °C		-56	
I_D	-Continuous	T _A = 25 °C	(Note 1a)	-14	Α
	-Pulsed		(Note 3)	-226	
D	Power Dissipation	T _C = 25 °C		30	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.3	VV
T _J , T _{STG}	Operating and Storage Junction Tempe	rature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC6688P	FDMC6688P	Power 33	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		-16		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -16 V, V _{GS} = 0 V			-1	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_{D} = -250 \mu A$	-0.4	-0.75	-1	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		3		mV/°C
	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -14 \text{ A}$		5.3	6.5	- mΩ
		$V_{GS} = -2.5 \text{ V}, I_D = -11 \text{ A}$		7	9.8	
r _{DS(on)}		$V_{GS} = -1.8 \text{ V}, I_D = -9 \text{ A}$		10.7	20	
		V_{GS} = -4.5 V, I_D = -14 A, T_J = 125 °C		7.3	11	
g _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, I_{D} = -14 \text{ A}$		80		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 40 V V - 0 V	4956	7435	pF
C _{oss}	Output Capacitance	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	678	1020	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	618	930	pF
R_{g}	Gate Resistance		4.5		Ω

Switching Characteristics

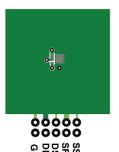
t _{d(on)}	Turn-On Delay Time		19	35	ns
t _r	Rise Time	V _{DD} = -10 V, I _D = -14 A,	33	53	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$	119	190	ns
t _f	Fall Time		68	109	ns
Q_g	Total Gate Charge	V 40.V L 44.A	44	61	nC
Q _{gs}	Gate to Source Charge	V _{DD} = -10 V, I _D = -14 A, V _{GS} = -4.5 V	7.4		nC
Q_{gd}	Gate to Drain "Miller" Charge	VGS4.0 V	11		nC

Drain-Source Diode Characteristics

V_{SD}	1Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -14 \text{ A}$ (Note 2)		-0.8	-1.2	\/
		$V_{GS} = 0 \text{ V}, I_{S} = -2 \text{ A}$ (Note 2)		-0.6	-1.2	v
t _{rr}	Reverse Recovery Time	L = 14 A di/dt = 100 A/		26	41	ns
Q _{rr}	Reverse Recovery Charge	I _F = -14 A, di/dt = 100 A/μs		10	20	nC

Notes:

1: R_{0,JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,JC} is guaranteed by design while R_{0,JA} is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2: Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0 %.
- 3: Pulse Id refers to Forward Bias Safe Operation Area.

Typical Characteristics T_J = 25 °C unless otherwise noted

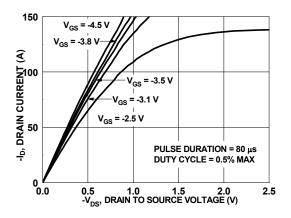


Figure 1. On Region Characteristics

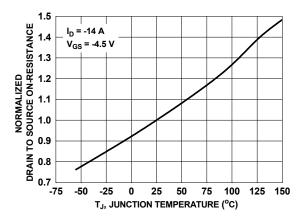


Figure 3. Normalized On Resistance vs Junction Temperature

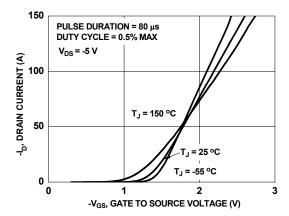


Figure 5. Transfer Characteristics

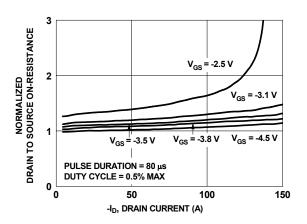


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

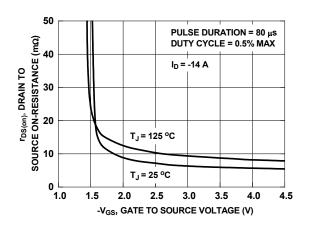


Figure 4. On-Resistance vs Gate to Source Voltage

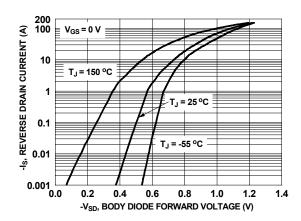


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

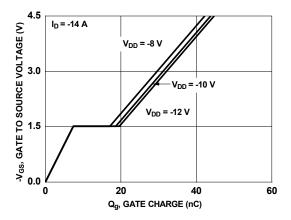


Figure 7. Gate Charge Characteristics

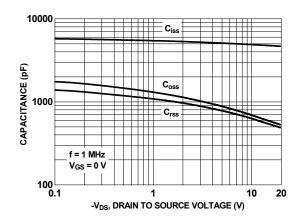


Figure 8. Capacitance vs Drain to Source Voltage

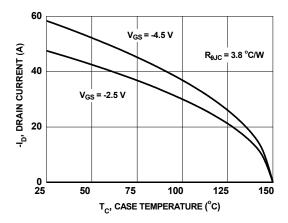


Figure 9. Maximum Continuous Drain Current vs Case Temperature

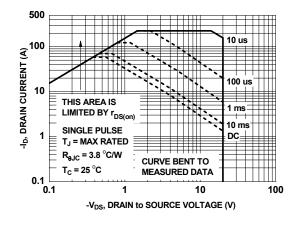


Figure 10. Forward Bias Safe Operating Area

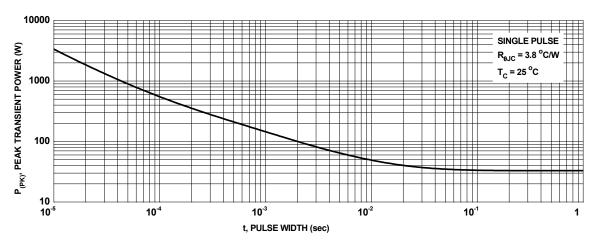


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

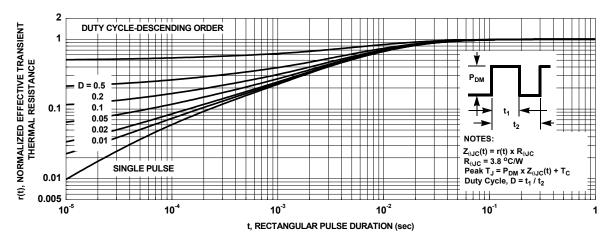
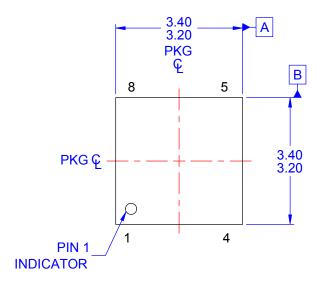
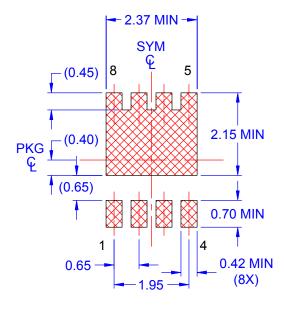
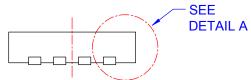


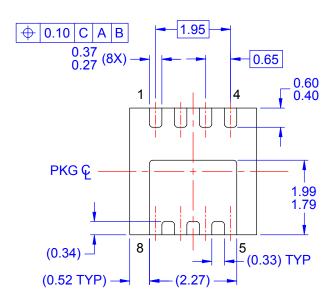
Figure 12. Junction-to-Case Transient Thermal Response Curve

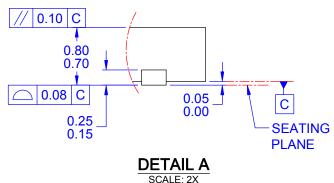












NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- E) DRAWING FILE NAME: MKT-PQFN08SREV1



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